

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Masayuki Yasuda

Docket No.: TIJ-24816

Serial No.: TBD

Art Unit: TBD

Filed: 2/5/98

Examiner: TBD

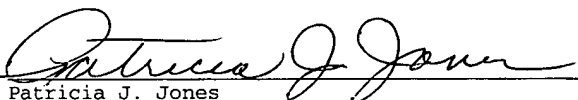
Title: Manufacturing Method of Semiconductor IC Device

PRELIMINARY AMENDMENT

2/5/98

Assistant Commissioner for Patents  
**Box New Patent Applications**  
Washington, D. C. 20231

"EXPRESS MAIL" mailing label number  
TB309670273US, Date of Deposit: 2/5/98. I  
hereby certify that the accompanying  
Application is being deposited with the United  
States Postal Service "Express Mail Post  
Office to Addressee" service under 37 CFR 1.10  
on the date indicated above and is addressed  
to the Assistant Commissioner for Patents,  
Washington, DC 20231.

  
Patricia J. Jones

Sir:

Prior to the examination of the above-identified application,  
Applicants respectfully submit the following amendments and remarks.

IN THE CLAIMS:

Please amend Claims 1-5 as follows:

1. (Amended) A manufacturing method of a semiconductor IC  
device, [characterized by the fact that it consists of] comprising  
the following steps [of operation]:

forming [a step in which] an insulating film [is formed] on a  
semiconductor substrate or SOI substrate;

forming [a step in which] a first mask film [is formed] on the  
[aforementioned] insulating film;